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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/727,662	12/05/2003	Jiro Matsumoto	F00ED0150-DIV	4972.
26071 JUNICHI MIM	7590 06/18/2007	1	EXAM	IINER
OKI AMERICA	A INC.		PHAM, LONG	
1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005			ART UNIT	PAPER NUMBER
			2814	
•				DEL HIERVI VODE
		•	MAIL DATE	DELIVERY MODE
			06/18/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

# Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)		
10/727,662	MATSUMOTO, JIRO		
Examiner	Art Unit		
Long Pham	2814		

	Long Pham	2814				
The MAILING DATE of this communication appe	ars on the cover sheet with the c	orrespondence add	ress			
THE REPLY FILED <u>16 May 2007</u> FAILS TO PLACE THIS APP	LICATION IN CONDITION FOR AL	LOWANCE.				
1.  The reply was filed after a final rejection, but prior to or on this application, applicant must timely file one of the follow places the application in condition for allowance; (2) a No a Request for Continued Examination (RCE) in compliance time periods:	ving replies: (1) an amendment, aff tice of Appeal (with appeal fee) in c	idavit, or other evider compliance with 37 C	rce, which FR 41.31; or (3)			
<ul> <li>a) The period for reply expires 3 months from the mailing date</li> <li>b) The period for reply expires on: (1) the mailing date of this A</li> </ul>		in the final rejection, wh	ichavar is later. In			
<ul> <li>b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire I Examiner Note: If box 1 is checked, check either box (a) or</li> </ul>	ater than SIX MONTHS from the mailing	g date of the final rejecti	on.			
TWO MONTHS OF THE FINAL REJECTION. See MPEP 7 Extensions of time may be obtained under 37 CFR 1.136(a). The date		36(a) and the appropria	te extension fee			
have been filed is the date for purposes of determining the period of exunder 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b) NOTICE OF APPEAL	tension and the corresponding amount shortened statutory period for reply orig r than three months after the mailing da	of the fee. The appropri inally set in the final Offi	ate extension fee ce action; or (2) as			
<ol> <li>The Notice of Appeal was filed on A brief in comp filing the Notice of Appeal (37 CFR 41.37(a)), or any exte a Notice of Appeal has been filed, any reply must be filed AMENDMENTS</li> </ol>	nsion thereof (37 CFR 41.37(e)), to	avoid dismissal of th	s of the date of e appeal. Since			
3. The proposed amendment(s) filed after a final rejection,	but prior to the date of filing a brief.	will not be entered be	ecause			
(a) They raise new issues that would require further co	nsideration and/or search (see NO					
<ul><li>(b) ☐ They raise the issue of new matter (see NOTE belo</li><li>(c) ☐ They are not deemed to place the application in beto</li></ul>		ducing or simplifying	the issues for			
appeal; and/or (d) They present additional claims without canceling a	corresponding number of finally rei	ected claims				
NOTE: (See 37 CFR 1.116 and 41.33(a)).	oorroopenang namber or imany rej	ootoa olamio.	,			
4. The amendments are not in compliance with 37 CFR 1.1  5. Applicant's reply has overcome the following rejection(s)		mpliant Amendment	PTOL-324).			
<ol> <li>Newly proposed or amended claim(s) would be all non-allowable claim(s).</li> </ol>		timely filed amendme	nt canceling the			
<ol> <li>For purposes of appeal, the proposed amendment(s): a) how the new or amended claims would be rejected is pro-</li> </ol>		II be entered and an e	explanation of			
The status of the claim(s) is (or will be) as follows: Claim(s) allowed:						
Claim(s) objected to:						
Claim(s) rejected: Claim(s) withdrawn from consideration:						
AFFIDAVIT OR OTHER EVIDENCE						
<ol> <li>The affidavit or other evidence filed after a final action, but because applicant failed to provide a showing of good an was not earlier presented. See 37 CFR 1.116(e).</li> </ol>						
<ol> <li>The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to o</li> </ol>	overcome <u>all</u> rejections under appea	al and/or appellant fai	ls to provide a			
showing a good and sufficient reasons why it is necessary and was not earlier presented. See 37 CFR 41.33(d)(1).  The affidavit or other evidence is entered. An explanation of the status of the claims after entry is below or attached.						
REQUEST FOR RECONSIDERATION/OTHER  11. The request for reconsideration has been considered but does NOT place the application in condition for allowance because:						
See attached office action.		i condition for allowal	ice because:			
<ul><li>12. ☐ Note the attached Information Disclosure Statement(s).</li><li>13. ☐ Other:</li></ul>	(PTO/SB/08) Paper No(s)					
		Long Dham				
		Long Pham Primary Examiner Art Unit: 2814				

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### **Advisory Action**

#### Status of Amendment after final

The response after final dated 05/16/07 has been entered.

#### Status of pending claims

See the final rejection dated 02/27/07.

## Response to Arguments

Applicant's arguments filed 05/16/07 have been fully considered but they are not persuasive. See below.

In response to the applicant's arguments in the paragraph at the bottom of page 2 of the response dated 05/16/07, it is submitted that claims 1 and 32 as written do not require the limitation of "semiconductor wafer is not mounted in the second area".

In response to the applicant's arguments in the paragraph at the middle page 3 of the response dated 05/16/07, it is submitted that uneven surface or slits (98, 76a, 98a, and 77) are not formed at the edge or the periphery of lower mold 21 of fig. 17 of Miyajima.

In response to the applicant's arguments regarding claim 6 on page 4 of the response dated 05/16/07, it is submitted that Miyajima teaches the uneven surface is formed by slits.

In response to the applicant's arguments in the paragraph at the bottom of page 4 of the response dated 05/16/07, it is submitted that the areas where the uneven surfaces or slits are defined as or interpreted as the second area.

In response to the applicant's arguments in the paragraph at the middle page 3 of the response dated 05/16/07, it is submitted that the area where the semiconductor wafer is formed is broadly defined the area cover the entire apparatus including the shock absorbers 78. Note that claim language must be given broadest interpretation during the examination of the application.

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In response to the applicant's arguments in the paragraph at the top of page 9 of the response dated 05/16/07, it is submitted that the prior art motivation or advantage may be different that that of applicants while still supporting a conclusion of obviousness. In Re Wiseman 201 USPQ 658 (CCPA); Ex Parte Obiaya 227 USPQ 58 (Bd. of App. 1985).

In response to the applicant's arguments in the paragraph at the top of page 10 of the response dated 05/16/07, it is submitted that the applicant has the burden of proving the criticality of the claimed range.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Long Pham whose telephone number is 571-272-1714. The examiner can normally be reached on Mon-Frid, 10am to 5pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on 571-272-1705. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

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Long Pham

Primary Examiner

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